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Infineon joins Fraunhofer in system-in-package project

by Richard Wilson
Wednesday 09 December 2009 04:40

A German research project will look at new ways of designing multi-chip system-in-package (SiP) devices with tools that replicate the level of design automation already seen in single chip SoC devices.

The project, called CoSiP, includes a number of German companies and research institutes. Infineon Technologies, the Fraunhofer Institute for Reliability and Microintegration, the automotive electronics division of Bosch and Siemens healthcare are all contributing to the project.

The aim of the work is to combine the design of silicon, chip package and the board or substrate within the SiP into a single design flow.

The hope is this will introduce the types of efficiencies that are already seen in the design of SoC devices.

The four company partners are funding about 50% of the CoSiP research project which is co-funded by the German Federal Ministry of Education and Research (BMBF), is due to be completed by the end of 2012.

The project work is being carried out in close cooperation with the European MEDEA+ project "Chip/Package-System Co-Design - An Enabler for Compact System-in-Package Solutions".

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